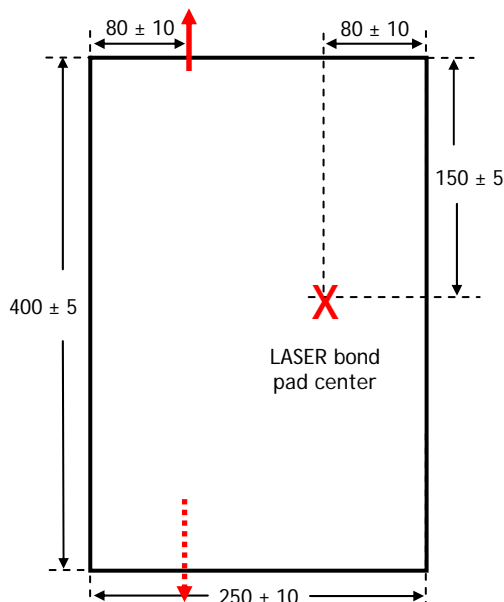
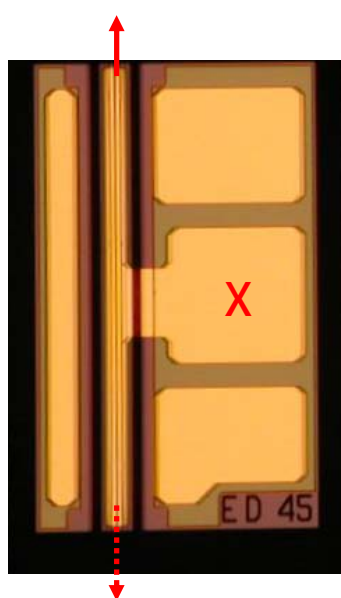


ABSOLUTE MAXIMUM RATINGS						
Parameter	Condition	Symbol	Min.	Typ.	Max.	Unit
Submount Temperature		T	0	-	85	°C
Storage Temperature		T _{St}	-40	-	100	°C
Optical Output Power	CW	P _o	-	-	15	mW
Laser Reverse Voltage		V _R	-	-	2	V
Laser Forward Current		I _F	-	-	150	mA

PHYSICAL CHARACTERISTICS			
Parameter	Symbol	Typical	Unit
Bond Pad	l x w	100 x 100	μm
Chip Dimensions	l x w x h	400 x 250 x 100	μm



ORDERING INFORMATION	
Part Number	Description
131D-02C-LWF11-S01	1310 DFB EEL, 2.5G, Commercial Temp (0 to 70°C), Wafer level
131D-02E-LWF11-S01	1310 DFB EEL, 2.5G, Extended Temp (-20 to 85°C), Wafer level
131D-02F-LWF11-S01	1310, DFB EEL, 2.5G, Extended Industrial Temp (up to 95°C), Wafer level ¹
131D-02C-LCT11-S01	1310 DFB EEL, 2.5G, Commercial Temp (0 to 70°C), chip-on-tape
131D-02E-LCT11-S01	1310, DFB EEL, 2.5G, Extended Temp (-20 to 85°C), chip-on-tape
131D-02F-LCT11-S01	1310, DFB EEL, 2.5G, Extended Industrial Temp (up to 95°C), chip-on-tape ¹
131D-02C-LCG11-S01	1310 DFB EEL, 2.5G, Commercial Temp (0 to 70°C), chip on GelPack
131D-02E-LCG11-S01	1310, DFB EEL, 2.5G, ExtendedTemp (-20 to 85°C), chip on GelPack
131D-02F-LCG11-S01	1310 DFB EEL, 2.5G, Extended Industrial Temp (up to 95°C), chip on GelPack ¹

1. Lower end of temperature range TBD